Part no. Article no. Catalog No. IKT-BI-3854/SKAP

147526

IKT-BI-3854-SKAP



Design verification as per IEC/EN 61439

Heat dissipation, at an ambient temperature of 35°C, delta T: 20 degrees, calculated as per IEC 60890 Individual enclosure for wall mounting Pv C0 38 Starting enclosure for wall mounting Pv C0 33 Middle enclosure for wall mounting Pv C0 33 Heat dissipation, at an ambient temperature of 35°C, delta T: 35 degrees, calculated as per IEC 60890 Individual enclosure for wall mounting Pv C0 77 Starting enclosure for wall mounting Pv C0 72 Middle enclosure for wall mounting Pv C0 66				
Individual enclosure for wall mounting Py CO 36 Middle enclosure for wall mounting Py CO 36 Middle enclosure for wall mounting Py CO 36 Middle enclosure for wall mounting Py CO 37 Head dissipation, at an ambient temperature of 35°C, delta T.35 degrees, calculated as per IEC 68890 Individual enclosure for wall mounting Py CO 77 Starting enclosure for wall mounting Py CO 72 Middle enclosure for wall mounting Py CO 75 Middle enclosure for wall mounting Mests the product standard's requirements. Meets the product standard's requirements. In 10.2.5 Meets the product standard's requi	Technical data for design verification			
Starting anciosure for wall mounting Middle onclosure for wall mounting Py CO 33 Head dissipation, at an ambient temperature of 35°C, delta T:35 degrees, calculated as par ELC 60893 Individual anciosure for wall mounting Py CO 77 Starting enclosure for wall mounting Py CO 72 Middle onclosure for wall mounting Py CO 75 Middle onclosure for wall mounting Middle onclosure for wall mounting Py CO 75 Middle onclosure for wall mounting Middle onclosure for wall mounting Py CO 75 Middle onclosure for wall mounting Middle onclosure for wall mounting Py CO 75 Middle onclosure for wall mounting Middle onclosure for wall mounting Py CO 75 Meets the product standard's requirements. Most relevant to indoor installations. Does not apply to enclosures without lifting aids. Not relevant to indoor installations. Does not apply to enclosures without lifting aids. Not relevant to indoor installations. 10.2.5 Lifting 10.2.5 Lifting 10.2.5 Lifting 10.2.6 Meets the product standard's requirements. 10.3 Degree of protection of ASSEMBLIES 10.4 Resistance to ultra-violet (UV) radiation 10.5 Protection of ASSEMBLIES 10.6 Connection of ASSEMBLIES 10.7 Inscriptions 10.8 Protection of ASSEMBLIES 10.9 Insulation properties 10.9 I				
Middle enclosure for wall mounting Heat dissipation, at an ambient temperature of 35°C, delta T.35 degrees, calculated as per IEC 60800 m. Comment of the content of the c	Individual enclosure for wall mounting	P_{V}	CO	38
Heat dissipation, at an ambient temperature of 35°C, delta 1: 33 degrees, calculated as per ICE 08909 Individual enclosure for wall mounting Py 00 72 Starting enclosure for wall mounting Py 00 72 Middle enclosure for wall mounting Py 00 66 ECCEN 61439 design verification 10.2 Strength of materials and parts 10.2.2 Corrosion resistance 10.2.2 Verification of themal stability of enclosures 10.2.3 Verification of resistance of insulating materials to normal heat and fire due to internal electric effects 10.2.3 Verification of resistance of insulating materials to abnormal heat and fire due to internal electric effects 10.2.4 Resistance to ultra-violet (UV) radiation 10.2.5 Ithing 10.2.6 Mechanical impact 10.2.7 Inscriptions 10.3 Opere of protection of ASSEMBLIES 10.3 Opere of protection against electric shock 10.5 Flotacion against electric shock 10.5 Incorporation of switching devices and components 10.3 Insulation properties 10.3 Opere-frequency electric strength 10.3 Insulation properties 10.3 Sampulse withstand voltage 10.3 Impulse withstand voltage 10.4 Team and electric currents and connections 10.5 Incorporation of switching devices and components 10.5 Incorporation of switching devices and connections 10.5 Incor	Starting enclosure for wall mounting	P_{V}	CO	36
Label	Middle enclosure for wall mounting	P_{V}	CO	33
Starting enclosure for wall mounting Middle enclosure for wall mounting Py C0 66 ECC/N 61439 design verification 10.2 Strength of materials and parts 10.2.2 Corrosion resistance 10.2.3 I Verification of thermal stability of enclosures 10.2.3 Verification of thermal stability of enclosures 10.2.3 Verification of resistance of insulating materials to abnormal heat and fire due to internal electric effects 10.2.4 Resistance to ultra-violet (UV) radiation 10.2 Eliting 10.2 Mechanical impact 10.2.5 Lifting 10.3 Degree of protection of ASSEMBLIES 10.3 Degree of protection of ASSEMBLIES 10.4 Clearances and creepage distances 10.5 Protection against electric shock 10.6 Connections for external conductors 10.8 Connections for external conductors 10.9 Insulation properties 10.9 Insulation propertie				
Middle enclosure for wall mounting Py CD 65 ECVEN 61439 design verification 10.2 Strength of materials and parts 10.2.2 Corrosion resistance 10.2.3.1 Verification of thermal stability of enclosures 10.2.3.2 Verification of resistance of insulating materials to normal heat 10.2.3.2 Verification of resistance of insulating materials to abnormal heat 10.2.3 Streing of enclosures of insulating materials to abnormal heat 10.2.4 Resistance to ultra-violet (UV) radiation 10.2.5 Lifting 10.2.6 Mechanical impact 10.2.7 Inscriptions 10.3.0 legree of protection of ASSEMBLIES 10.3.0 legree of protection against electric shock 10.4.1 Clearances and creepage distances 10.5 Protection against electric shock 10.6 Incorporation of switching devices and components 10.8 Connections for external conductors 10.9 assistance to connections 10.9 assistance to external conductors 10.9 assistance or external conductors 10.9 assistance for external	Individual enclosure for wall mounting	P_{V}	CO	77
EC/EN 61439 design verification 10.2 Strength of materials and parts 10.2.2 Corrosion resistance 10.2.3.1 Verification of thermal stability of enclosures 10.2.3.2 Verification of resistance of insulating materials to normal heat 10.2.3.2 Verification of resistance of insulating materials to normal heat 10.2.3.3.2 Verification of resistance of insulating materials to abnormal heat 10.2.3.3.4 Verification of resistance of insulating materials to abnormal heat 10.2.4 Resistance to ultra-violet (UV) radiation 10.2.5 Lifting 10.2.6 Mechanical impact 10.2.7 Inscriptions 10.2.8 Mechanical impact 10.3.0 Egree of protection of ASSEMBLIES 10.3.0 Egree of protection of ASSEMBLIES 10.4 Clearances and creepage distances 10.5 Protection against electric shock 10.6 Incorporation of switching devices and components 10.6 Incorporation of switching devices and components 10.7 Internal electrical circuits and connections 10.9 Insulation properties 10.9.2 Power-frequency electric strength 10.9 Insulation properties 10.9.3 Impulse withstand voltage 10.9.4 Testing of enclosures made of insulating material 10.10 Temperature rise 10.10 Temperature rise 10.10 Temperature rise 10.11 Short-circuit rating 10.12 Electromagnetic compatibility 10.15 Licromagnetic compatibility 10.16 Licroprosposibility 10.16 Incorporation of exclaration and connections 10.16 Incorporation of switching the vices and components 10.17 Internal electrical circuits and connections 10.18 Connections for external conductors 10.19 Insulation properties 10.19 Insulati	Starting enclosure for wall mounting	P_{V}	CO	72
10.2 Strength of materials and parts 10.2 Corrosion resistance 10.2.3.1 Verification of thermal stability of enclosures 10.2.3.2 Verification of resistance of insulating materials to normal heat 10.2.3.2 Verification of resistance of insulating materials to normal heat and fire due to internal electric effects 10.2.4 Resistance to ultra-violet (UV) radiation 10.2.5 Lifting 10.2.5 Lifting 10.2.5 Mechanical impact 10.2.7 Inscriptions 10.2.6 Mechanical impact 10.2.7 Inscriptions 10.4 Clearances and creepage distances 10.5 Portection against electric shock 10.5 Protection against electric shock 10.5 Protection against electric shock 10.6 Incorporation of switching devices and components 10.7 Internal electrical circuits and connections 10.9 Insulation properties 10.9.2 Power-frequency electric strength 10.9 Insulation properties 10.9.1 The panel builder's responsibility. 10.9 Insulation properties 10.9.1 The panel builder is responsibility. 10.9 Insulation properties 10.9.1 The panel builder is responsibility. 10.9 Insulation properties 10.9.2 Power-frequency electric strength 10.9 Insulation properties 10.9.1 The panel builder is responsibility. 10.9 Insulation properties 10.9.1 The panel builder is responsibility. 10.9 Insulation properties 10.9.2 Power-frequency electric strength 10.9 Insulation properties 10.9.3 Impulse withstand voltage 10.10 Temperature rise 10.11 Short-circuit rating 10.15 Electromagnetic compatibility. 11.5 Is the panel builder's responsibility.	Middle enclosure for wall mounting	P_{V}	CO	66
10.2.2 Corrosion resistance 10.2.3.1 Verification of thermal stability of enclosures Meets the product standard's requirements. 10.2.3.2 Verification of resistance of insulating materials to normal heat 10.2.3.3 Verification of resistance of insulating materials to abnormal heat and fire due to internal electric effects 10.2.4 Resistance to ultra-violet (UV) radiation 10.2.5 Lifting 10.2.5 Mechanical impact 10.2.5 Mechanical impact 10.2.7 Inscriptions 10.3.0 Egree of protection of ASSEMBLIES 10.4 Clearances and creepage distances 10.5 Protection against electric shock 10.6 Incorporation of switching devices and components 10.7 Internal electrical circuits and connections 10.8 Connections for external conductors 10.9 Power-frequency electric strength 10.9.1 Power-frequency electric strength 10.9.2 Power-frequency electric strength 10.9.3 Tengersture rise 10.10 Temperature rise 10.10 Temperature rise 10.10 Temperature rise 10.11 Short-circuit rating 10.12 Electromagnetic compatibility. 10.15 Lectromagnetic compatibility. 10.16 Lectromagnetic compatibility. 10.16 Lectromagnetic compatibility. 10.17 Lectromagnetic compatibility. 10.18 Lectromagnetic compatibility. 10.19 Temperature rise 10.10 Temperature rise 10.10 Temperature rise 10.10 Temperature rise 10.11 Short-circuit rating 10.12 Electromagnetic compatibility. 10.15 Lectromagnetic compatibility. 10.15 Lectromagnetic compatibility.	IEC/EN 61439 design verification			
10.2.3.1 Verification of thermal stability of enclosures Meets the product standard's requirements. 10.2.3.2 Verification of resistance of insulating materials to abnormal heat and fire due to internal electric effects Meets the product standard's requirements. 10.2.3 Verification of resistance of insulating materials to abnormal heat and fire due to internal electric effects Meets the product standard's requirements. 10.2.4 Resistance to ultra-violet (UV) radiation Not relevant to indoor installations. 10.2.5 Lifting Does not apply to enclosures without lifting aids. 10.2.6 Mechanical impact IKOB 10.2.7 Inscriptions Meets the product standard's requirements. 10.3 Degree of protection of ASSEMBLIES IP30 10.4 Clearances and creepage distances Is the panel builder's responsibility. 10.5 Protection against electric shock < 0.1 Ω; meets the product standard's requirements.	10.2 Strength of materials and parts			
10.2.3.2 Verification of resistance of insulating materials to normal heat 10.2.3.3 Verification of resistance of insulating materials to abnormal heat and fire due to internal electric effects 10.2.4 Resistance to ultra-violet (UV) radiation 10.2.5 Lifting 10.2.5 Lifting 10.2.6 Mechanical impact 10.2.7 Inscriptions 10.2.7 Inscriptions 10.3 Degree of protection of ASSEMBLIES 10.3 Degree of protection of ASSEMBLIES 10.4 Clearances and creepage distances 10.5 Protection against electric shock 10.5 Protection against electric shock 10.6 Incorporation of switching devices and components 10.7 Internal electrical circuits and connections 10.8 Connections for external conductors 10.9 Insulation properties 10.9.2 Power-frequency electric strength 10.9.2 Power-frequency electric strength 10.9.4 Testing of enclosures made of insulating material 10.10 Temperature rise 10.10 Temperature rise 10.10 Temperature rise 10.11 Short-circuit rating 10.12 Electromagnetic compatibility 10.14 Electromagnetic compatibility 10.15 Electromagnetic compatibility 10.16 Electromagnetic compatibility 10.17 Electromagnetic compatibility 10.18 Electromagnetic compatibility 10.19 Electromagnetic compatibility 10.10 Electromagnetic compatibility 10.10 Electromagnetic compatibility 10.10 Electromagnetic compatibility 10.10 Electromagnetic compatibility	10.2.2 Corrosion resistance			Meets the product standard's requirements.
10.2.3.3 Verification of resistance of insulating materials to abnormal heat and fire due to internal electric effects 10.2.4 Resistance to ultra-violet (UV) radiation 10.2.5 Lifting Does not apply to enclosures without lifting aids. 10.2.6 Mechanical impact 10.2.7 Inscriptions 10.2.7 Inscriptions Meets the product standard's requirements. 10.3 Degree of protection of ASSEMBLIES 10.4 Clearances and creepage distances 10.5 Protection against electric shock 10.6 Incorporation of switching devices and components 10.7 Internal electrical circuits and connections 10.8 Connections for external conductors 10.9 Insulation properties 10.9.2 Power-frequency electric strength 10.9.2 Power-frequency electric strength 10.9.3 Impulse withstand voltage 10.9.4 Testing of enclosures made of insulating material 10.10 Temperature rise 10.10 Temperature rise The panel builder's responsibility. 10.11 Short-circuit rating 10.12 Electromagnetic compatibility 10.12 Electromagnetic compatibility 10.12 Electromagnetic compatibility 10.14 Step panel builder's responsibility. 11.15 the panel builder's responsibility. 12.5 kV 13.11 Short-circuit rating 14. The panel builder's responsibility. 15. The panel builder's responsibility. 16. The panel builder's responsibility. 17. The panel builder's responsibility. 18. The panel builder's responsibility. 19. The panel builder's responsibility. 10. The panel builder's responsibility.	10.2.3.1 Verification of thermal stability of enclosures			Meets the product standard's requirements.
and fire due to internal electric effects 10.2.4 Resistance to ultra-violet (UV) radiation 10.2.5 Lifting Does not apply to enclosures without lifting aids. 10.2.6 Mechanical impact 10.2.7 Inscriptions Meets the product standard's requirements. 10.3 Degree of protection of ASSEMBLIES 10.4 Clearances and creepage distances 10.5 Protection against electric shock 10.6 Incorporation of switching devices and components 10.7 Internal electrical circuits and connections 10.8 Connections for external conductors 10.9 Insulation properties 10.9.2 Power-frequency electric strength 10.9.2 Power-frequency electric strength 10.9.4 Testing of enclosures made of insulating material 10.10 Temperature rise 10.10 Temperature rise 10.11 Short-circuit rating 10.12 Electromagnetic compatibility 10 time panel builder's responsibility. 10 the panel builder's responsibility. 10 the panel builder is responsibility. 10 the panel builder is responsibility. 10 the panel builder is responsibility. 10.11 Short-circuit rating 10 the panel builder is responsibility.	10.2.3.2 Verification of resistance of insulating materials to normal heat			Meets the product standard's requirements.
10.2.5 Lifting 10.2.6 Mechanical impact 10.2.7 Inscriptions 10.3 Degree of protection of ASSEMBLIES 10.3 Degree of protection of ASSEMBLIES 10.4 Clearances and creepage distances 10.5 Protection against electric shock 10.5 Protection against electric shock 10.6 Incorporation of switching devices and components 10.7 Internal electrical circuits and connections 10.8 Connections for external conductors 10.9 Insulation properties 10.9.2 Power-frequency electric strength 10.9.3 Impulse withstand voltage 10.9.4 Testing of enclosures made of insulating material 10.10 Temperature rise 10.10 Temperature rise 10.11 Short-circuit rating 10.12 Electromagnetic compatibility IK08 Meets the product standard's requirements. IP30 Meets the product standard's requirements. IP30 Vol. 10.10 meets the product standard's requirements. Is the panel builder's responsibility. IV = 400 V AC 2.5 kV Does not apply to metal enclosures. The panel builder is responsibility. IS the panel builder's responsibility.				Meets the product standard's requirements.
10.2.6 Mechanical impact 10.2.7 Inscriptions Meets the product standard's requirements. 10.3 Degree of protection of ASSEMBLIES 10.4 Clearances and creepage distances 10.5 Protection against electric shock 10.6 Incorporation of switching devices and components 10.7 Internal electrical circuits and connections 10.8 Incorporation of switching devices and components 10.9 Internal electrical circuits and connections 10.9 Insulation properties 10.9.2 Power-frequency electric strength 10.9.3 Impulse withstand voltage 10.9.4 Testing of enclosures made of insulating material 10.10 Temperature rise 10.10 Temperature rise 10.11 Short-circuit rating 10.12 Electromagnetic compatibility 10.12 Electromagnetic compatibility 10.14 Electromagnetic compatibility 10.16 Engane I builder's responsibility. 10.17 Esting of enclosures made of insulations and insulations and insulations are calculation. Eaton will provide heat dissipation data for the devices.	10.2.4 Resistance to ultra-violet (UV) radiation			Not relevant to indoor installations.
10.2.7 Inscriptions Meets the product standard's requirements. 10.3 Degree of protection of ASSEMBLIES 10.4 Clearances and creepage distances Is the panel builder's responsibility. 10.5 Protection against electric shock 10.6 Incorporation of switching devices and components 10.7 Internal electrical circuits and connections 10.8 Connections for external conductors 10.9 Insulation properties 10.9.2 Power-frequency electric strength 10.9.3 Impulse withstand voltage 10.9.4 Testing of enclosures made of insulating material 10.10 Temperature rise 10.10 Temperature rise 10.11 Short-circuit rating 10.12 Electromagnetic compatibility Is the panel builder's responsibility. Is the panel builder is responsibility. Is the panel builder is responsibile for the temperature rise calculation. Eaton will provide heat dissipation data for the devices.	10.2.5 Lifting			Does not apply to enclosures without lifting aids.
10.3 Degree of protection of ASSEMBLIES 10.4 Clearances and creepage distances 10.5 Protection against electric shock 10.6 Incorporation of switching devices and components 10.7 Internal electrical circuits and connections 10.8 Connections for external conductors 10.9 Insulation properties 10.9.2 Power-frequency electric strength 10.9.3 Impulse withstand voltage 10.9.4 Testing of enclosures made of insulating material 10.10 Temperature rise 10.11 Short-circuit rating 10.12 Electromagnetic compatibility Is the panel builder's responsibility. Is the panel builder is responsibility of the temperature rise calculation. Eaton will provide heat dissipation data for the devices. Is the panel builder's responsibility. Is the panel builder's responsibility.	10.2.6 Mechanical impact			IK08
10.4 Clearances and creepage distances 10.5 Protection against electric shock 10.6 Incorporation of switching devices and components 10.7 Internal electrical circuits and connections 10.8 Connections for external conductors 10.9 Insulation properties 10.9.2 Power-frequency electric strength 10.9.3 Impulse withstand voltage 10.9.4 Testing of enclosures made of insulating material 10.10 Temperature rise 10.11 Short-circuit rating 10.12 Electromagnetic compatibility Is the panel builder's responsibility. Is the panel builder's responsibility. Is the panel builder's responsibility. Ui = 400 V AC 2.5 kV Does not apply to metal enclosures. The panel builder is responsible for the temperature rise calculation. Eaton will provide heat dissipation data for the devices. Is the panel builder's responsibility.	10.2.7 Inscriptions			Meets the product standard's requirements.
10.5 Protection against electric shock 10.6 Incorporation of switching devices and components 10.7 Internal electrical circuits and connections 10.8 Connections for external conductors 10.9 Insulation properties 10.9.2 Power-frequency electric strength 10.9.3 Impulse withstand voltage 10.9.4 Testing of enclosures made of insulating material 10.10 Temperature rise 10.11 Short-circuit rating 10.12 Electromagnetic compatibility 10.12 Electromagnetic compatibility 10.13 Short-circuit rating 10.14 Short-circuit compatibility 10.15 Short-circuit rating 10.16 Switch and components 10.17 Short-circuit rating 10.18 Short-circuit rating 10.19 Switch and components 10.19 Switch and components 10.10 Switch and components 10.10 Switch and components 10.11 Short-circuit rating 10.12 Electromagnetic compatibility 10.13 Short-circuit rating 10.14 Short-circuit rating 10.15 Switch and components 10.16 Switch and components 10.17 Switch and components 10.18 Switch and components 10.19 Switch and components 10.10 Switch and components 10.10 Switch and components 10.11 Short-circuit rating 10.12 Electromagnetic compatibility 10.13 Short-circuit rating 10.14 Switch and components 10.15 Switch and components 10.16 Switch and components 10.17 Switch and components 10.18 Switch and components 10.19 Switch and components 10.10 Switch and components 10.10 Switch and components 10.11 Switch and components 10.12 Switch and components 10.13 Switch and components 10.14 Switch and components 10.15 Switch and components 10.16 Switch and components 10.17 Switch and components 10.18 Switch and components 10.19 Switch and components 10.10 Switch and components 10.10 Switch and components 10.11 Switch and components 10.12 Switch and components 10.13 Switch and components 10.14 Switch and components 10.15 Switch and components 10.16 Switch and components 10.17 Switch and components 10.18 Switch and components 10.19 Switch and components 10.10 Switch and components 10.11 Switch and co	10.3 Degree of protection of ASSEMBLIES			IP30
10.6 Incorporation of switching devices and components 10.7 Internal electrical circuits and connections 10.8 Connections for external conductors 10.9 Insulation properties 10.9.2 Power-frequency electric strength 10.9.3 Impulse withstand voltage 10.9.4 Testing of enclosures made of insulating material 10.10 Temperature rise 10.10 Temperature rise 10.11 Short-circuit rating 10.12 Electromagnetic compatibility Is the panel builder's responsibility.	10.4 Clearances and creepage distances			Is the panel builder's responsibility.
10.7 Internal electrical circuits and connections 10.8 Connections for external conductors 10.9 Insulation properties 10.9.2 Power-frequency electric strength 10.9.3 Impulse withstand voltage 10.9.4 Testing of enclosures made of insulating material 10.10 Temperature rise 10.10 Short-circuit rating 10.12 Electromagnetic compatibility Is the panel builder's responsibility.	10.5 Protection against electric shock			$<$ 0.1 $\Omega;$ meets the product standard's requirements.
10.8 Connections for external conductors 10.9 Insulation properties 10.9.2 Power-frequency electric strength 10.9.3 Impulse withstand voltage 2.5 kV 10.9.4 Testing of enclosures made of insulating material 10.10 Temperature rise The panel builder is responsible for the temperature rise calculation. Eaton will provide heat dissipation data for the devices. 10.11 Short-circuit rating Is the panel builder's responsibility. 10.12 Electromagnetic compatibility Is the panel builder's responsibility.	10.6 Incorporation of switching devices and components			Is the panel builder's responsibility.
10.9 Insulation properties 10.9.2 Power-frequency electric strength 10.9.3 Impulse withstand voltage 2.5 kV 10.9.4 Testing of enclosures made of insulating material 10.10 Temperature rise 10.11 Short-circuit rating 10.12 Electromagnetic compatibility U _i = 400 V AC Does not apply to metal enclosures. The panel builder is responsible for the temperature rise calculation. Eaton will provide heat dissipation data for the devices. Is the panel builder's responsibility.	10.7 Internal electrical circuits and connections			Is the panel builder's responsibility.
10.9.2 Power-frequency electric strength 10.9.3 Impulse withstand voltage 2.5 kV 10.9.4 Testing of enclosures made of insulating material 10.10 Temperature rise The panel builder is responsible for the temperature rise calculation. Eaton will provide heat dissipation data for the devices. 10.11 Short-circuit rating Is the panel builder's responsibility. 10.12 Electromagnetic compatibility Is the panel builder's responsibility.	10.8 Connections for external conductors			Is the panel builder's responsibility.
10.9.3 Impulse withstand voltage 2.5 kV 10.9.4 Testing of enclosures made of insulating material 10.10 Temperature rise The panel builder is responsible for the temperature rise calculation. Eaton will provide heat dissipation data for the devices. 10.11 Short-circuit rating Is the panel builder's responsibility. 10.12 Electromagnetic compatibility Is the panel builder's responsibility.	10.9 Insulation properties			
10.9.4 Testing of enclosures made of insulating material Does not apply to metal enclosures. The panel builder is responsible for the temperature rise calculation. Eaton will provide heat dissipation data for the devices. 10.11 Short-circuit rating Is the panel builder's responsibility. 10.12 Electromagnetic compatibility Is the panel builder's responsibility.	10.9.2 Power-frequency electric strength			U _i = 400 V AC
10.10 Temperature rise The panel builder is responsible for the temperature rise calculation. Eaton will provide heat dissipation data for the devices. 10.11 Short-circuit rating Is the panel builder's responsibility. 10.12 Electromagnetic compatibility Is the panel builder's responsibility.	10.9.3 Impulse withstand voltage			2.5 kV
provide heat dissipation data for the devices. 10.11 Short-circuit rating Is the panel builder's responsibility. 10.12 Electromagnetic compatibility Is the panel builder's responsibility.	10.9.4 Testing of enclosures made of insulating material			Does not apply to metal enclosures.
10.12 Electromagnetic compatibility Is the panel builder's responsibility.	10.10 Temperature rise			
	10.11 Short-circuit rating			Is the panel builder's responsibility.
10.13 Mechanical function Meets the product standard's requirements.	10.12 Electromagnetic compatibility			Is the panel builder's responsibility.
	10.13 Mechanical function			Meets the product standard's requirements.